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Fig. 1

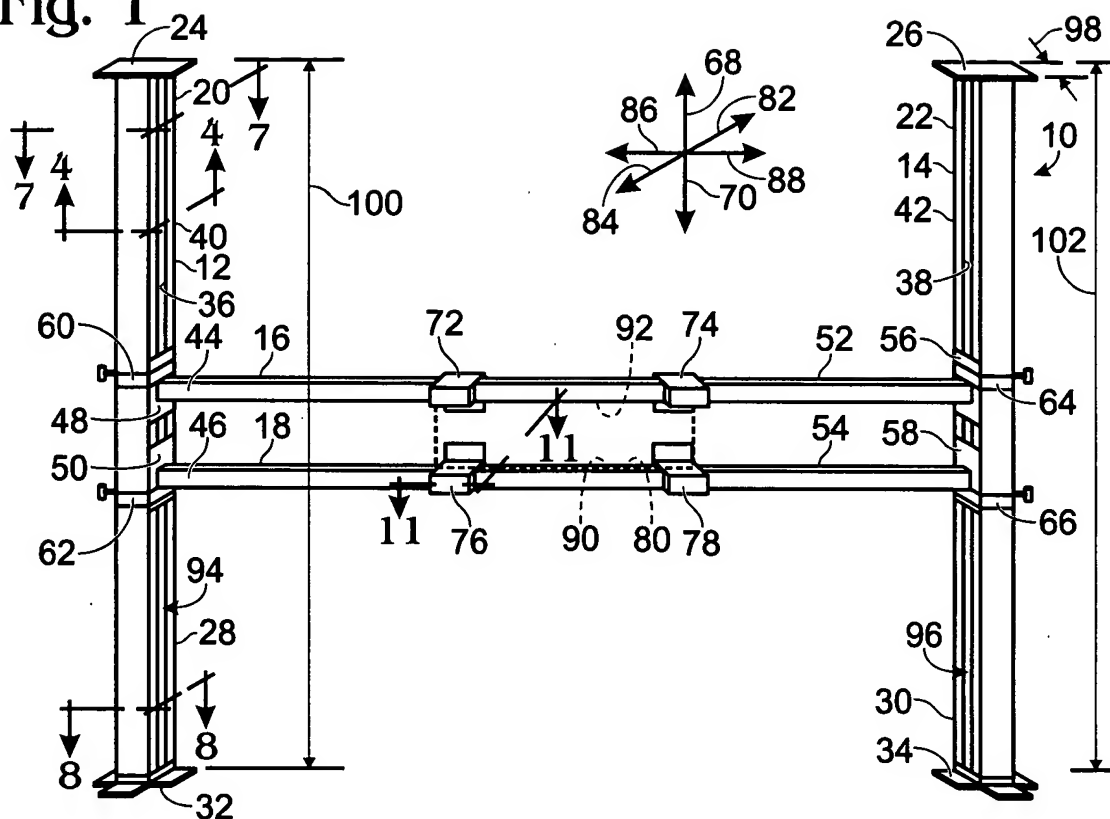
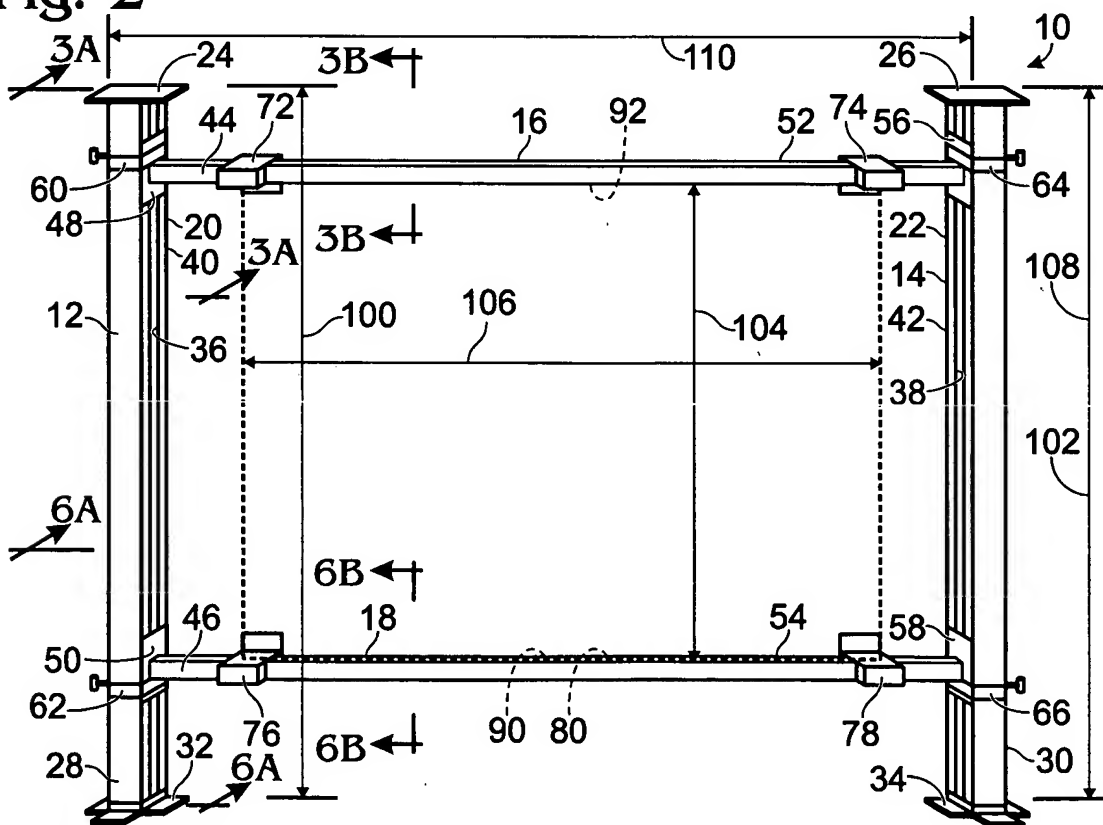
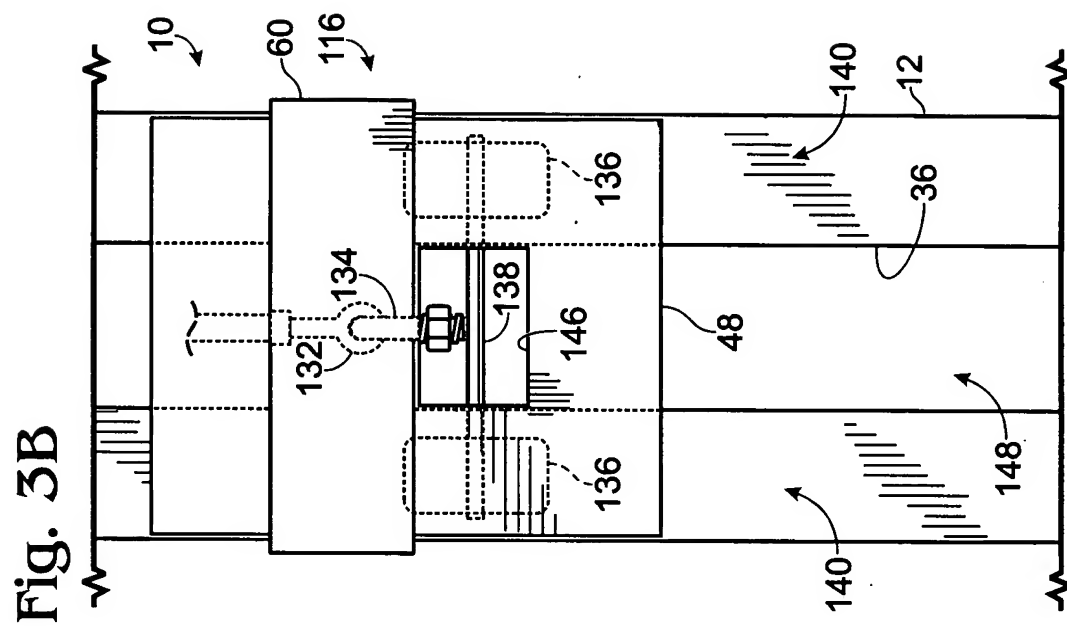
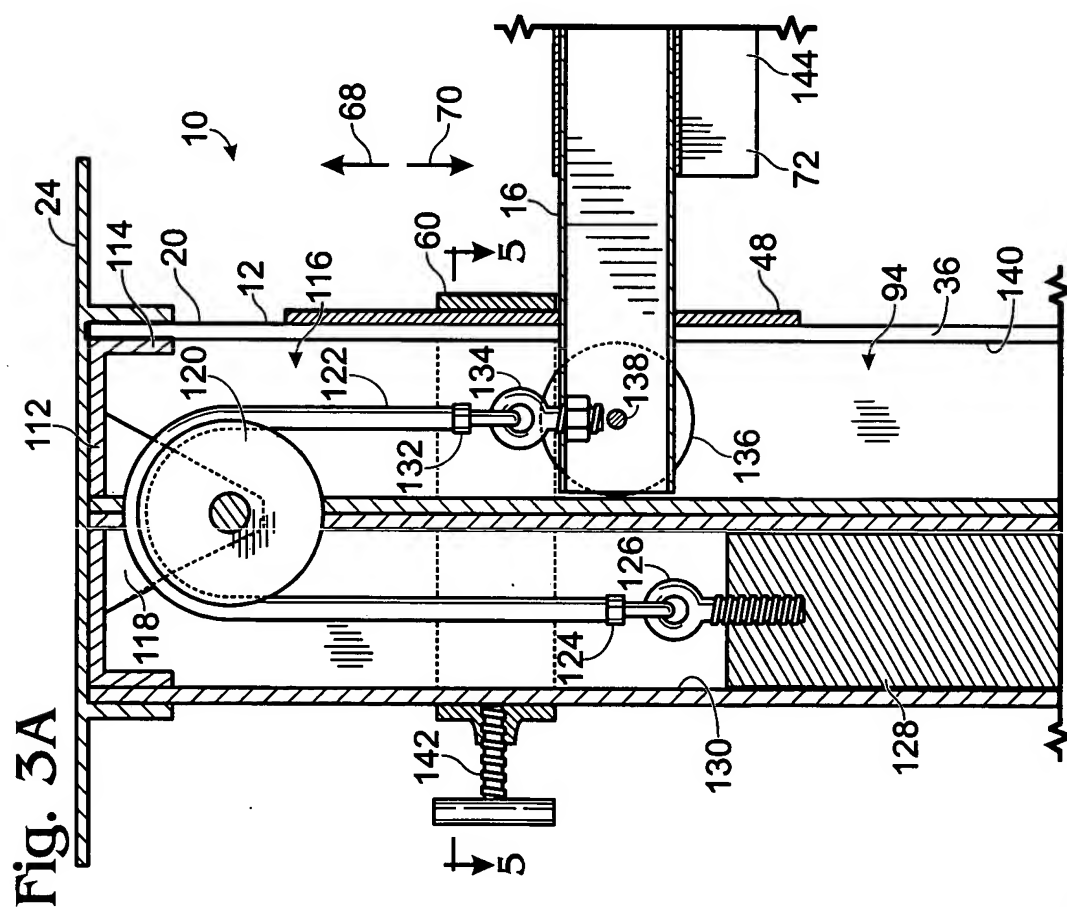
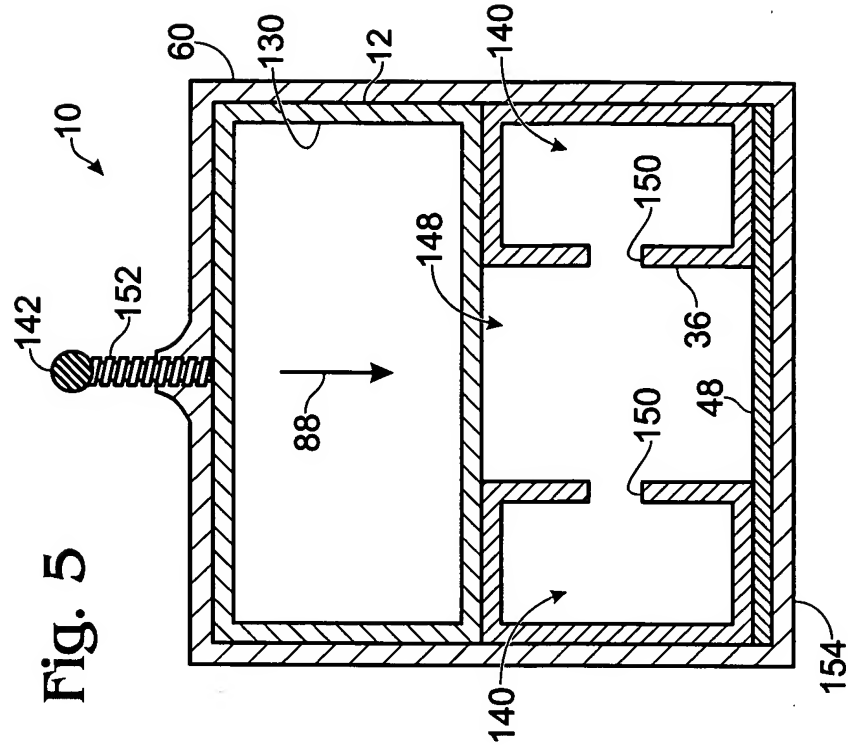
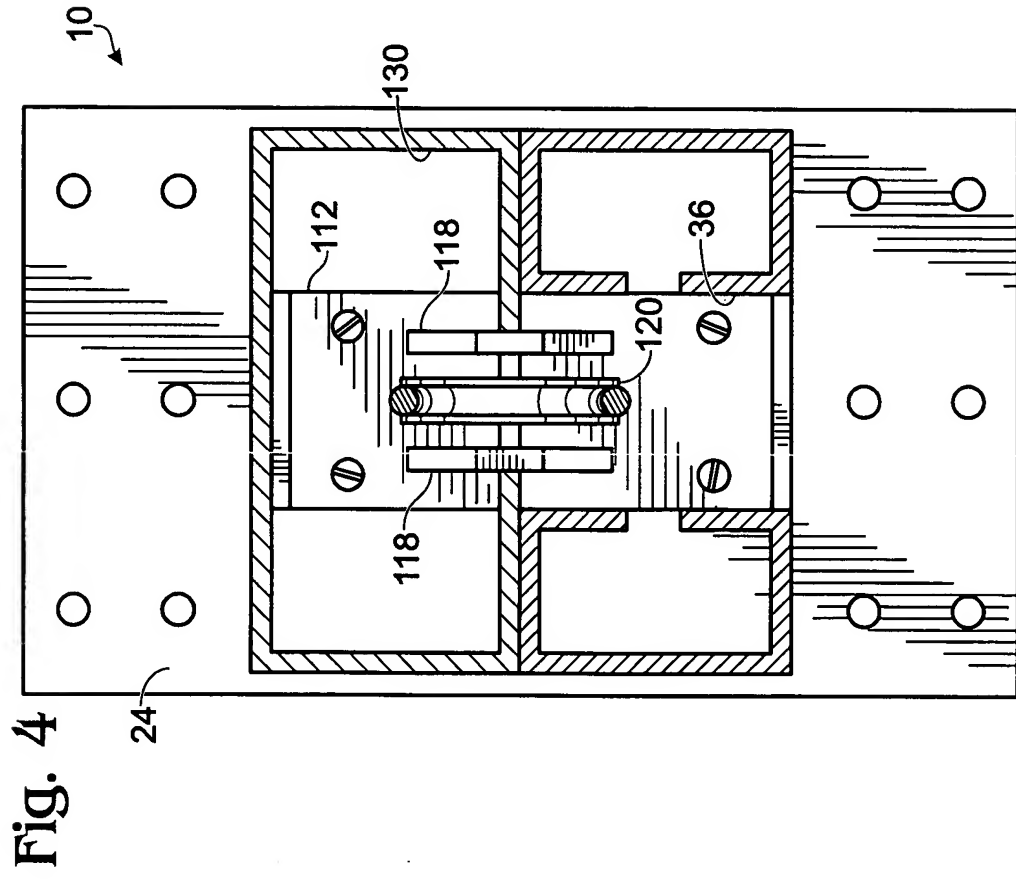


Fig. 2







A cross-sectional view of a device 10. The device features a central assembly 12. Within this assembly, there are two rectangular blocks 136, a central component 138, and a component 162. A layer 140 is positioned above the central assembly, and another layer 140 is below it. A component 148 is located to the right of the central assembly, and a component 156 is to the left. A component 62 is shown at the top of the central assembly. The entire device is enclosed within a frame 10.

Fig. 7

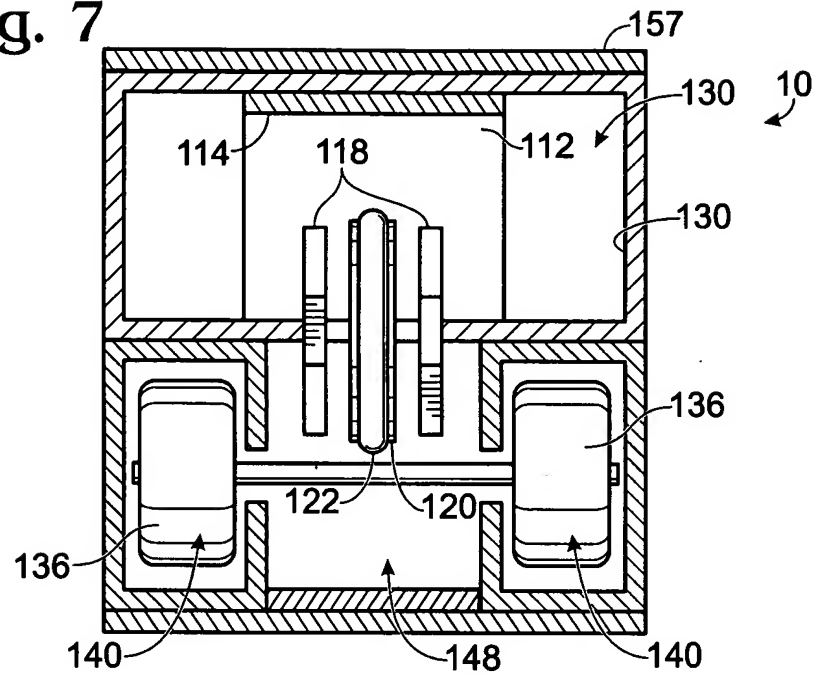


Fig. 8

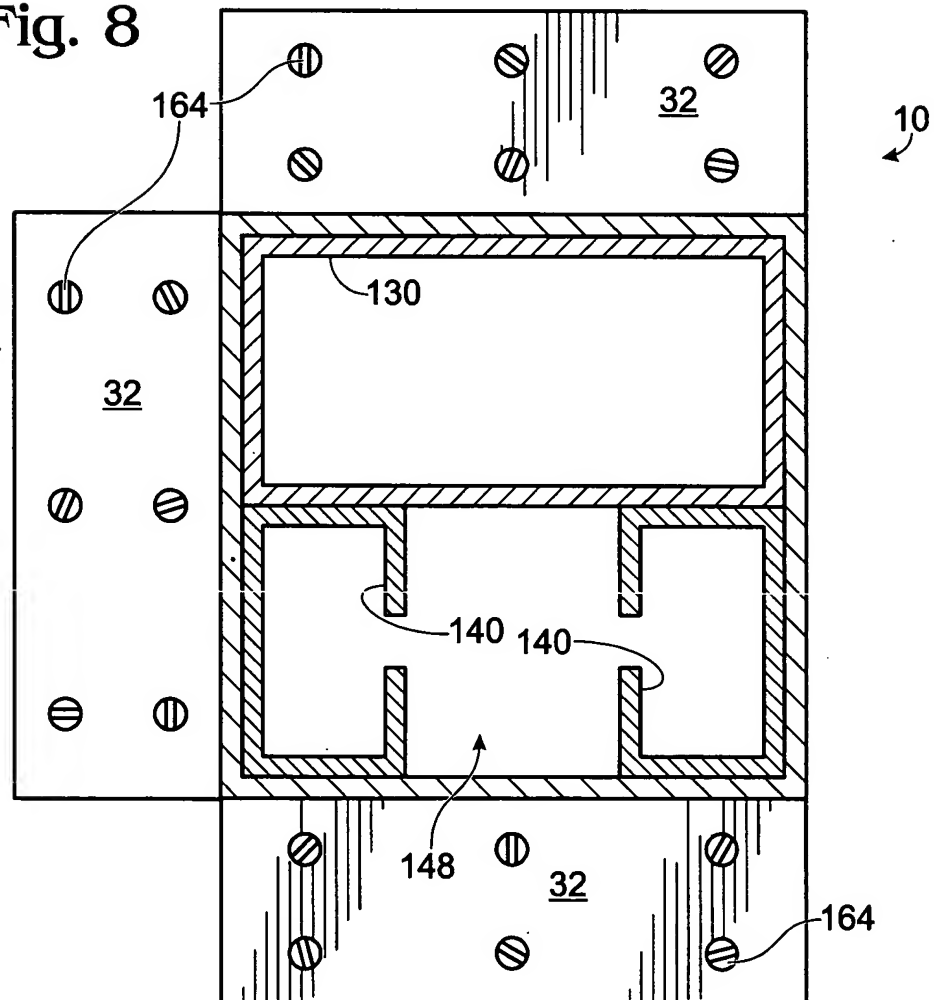


Fig. 9

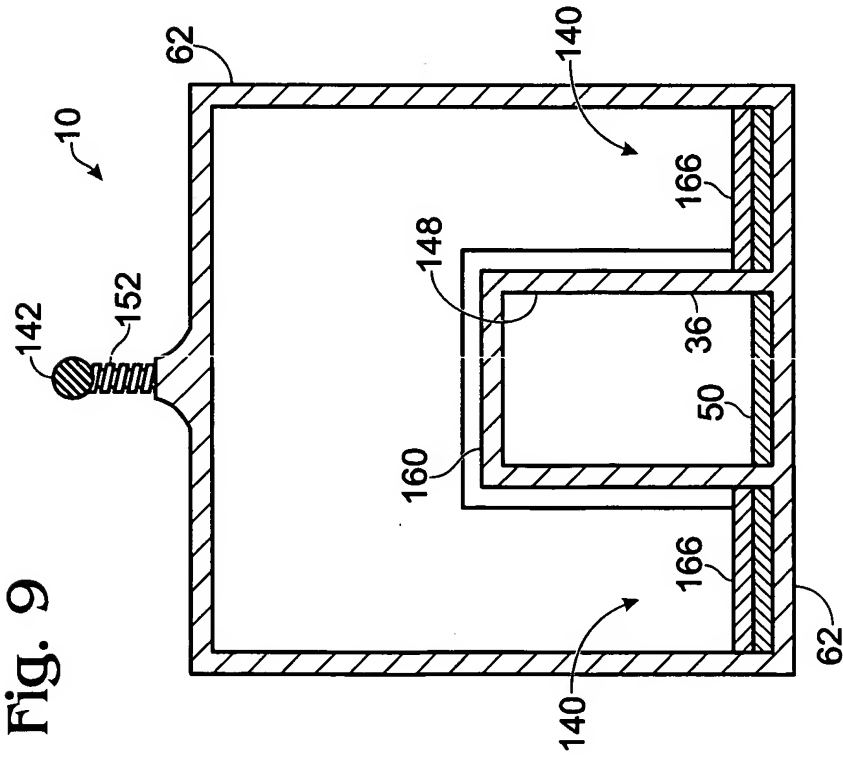


Fig. 10

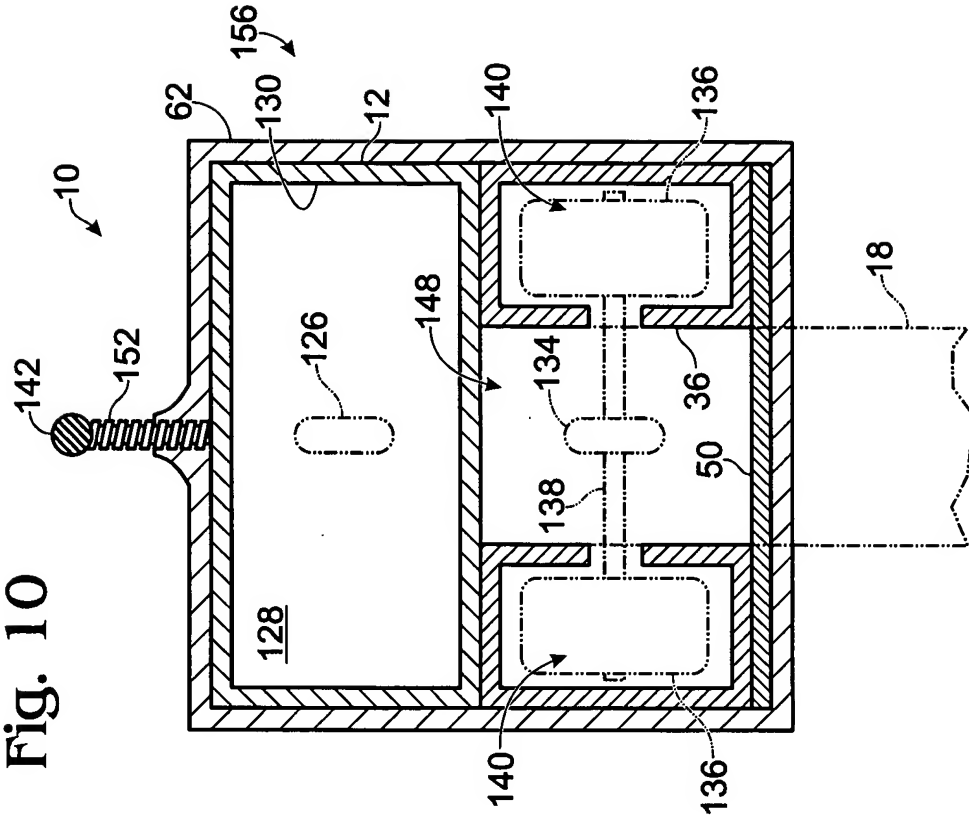


Fig. 11

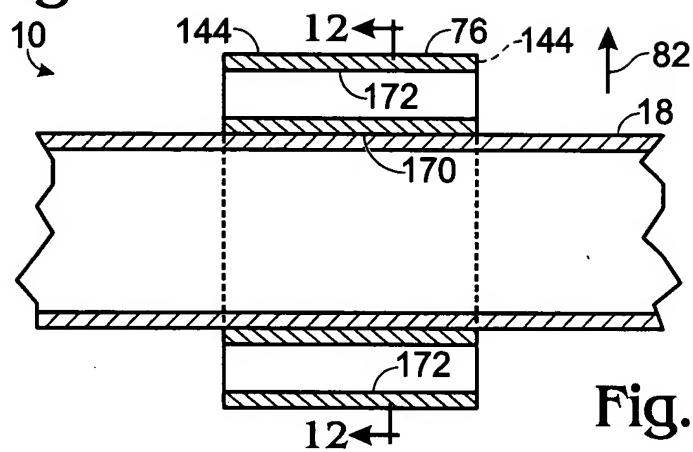


Fig. 12

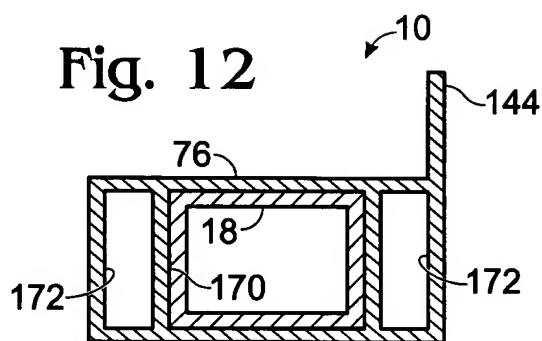


Fig. 13

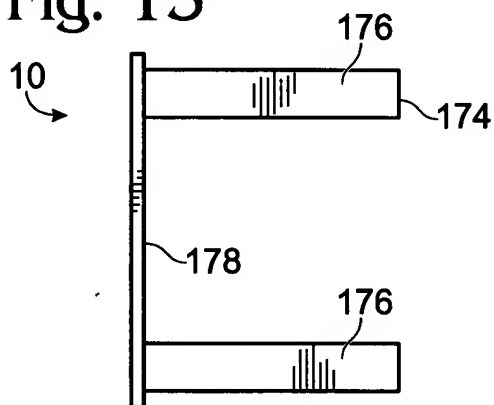


Fig. 14

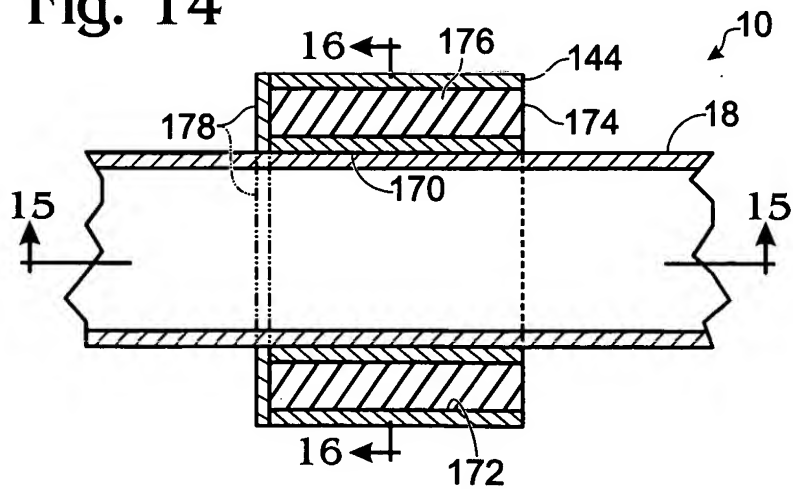


Fig. 15

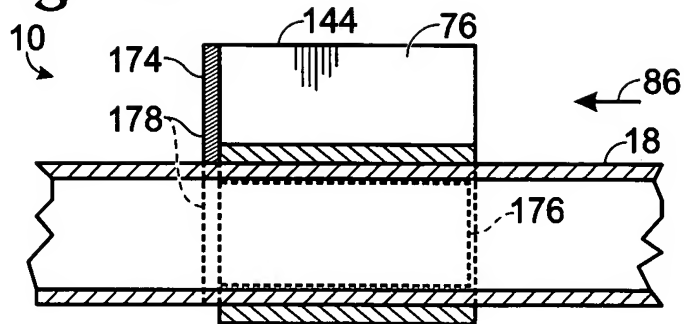


Fig. 16

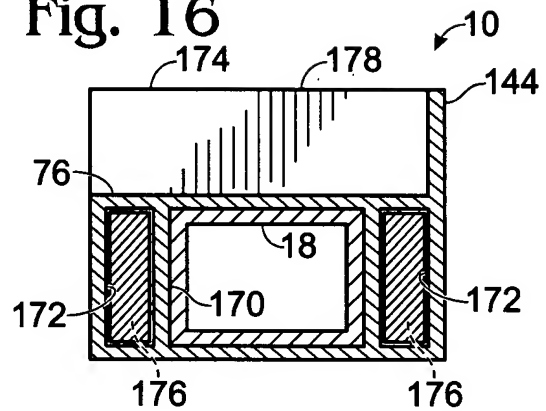


Fig. 17

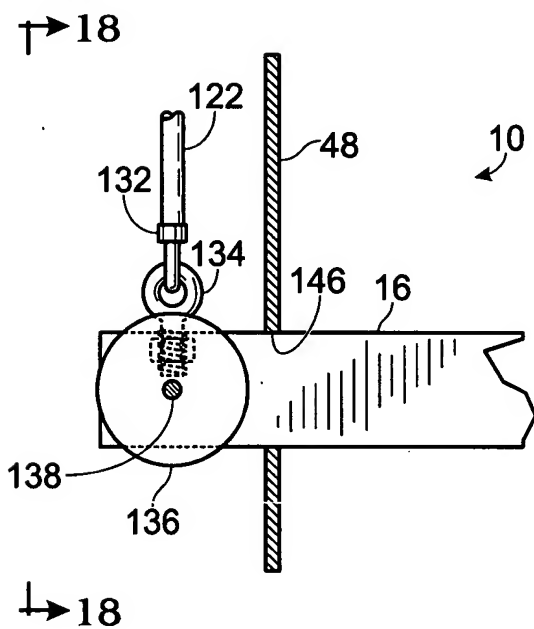


Fig. 18

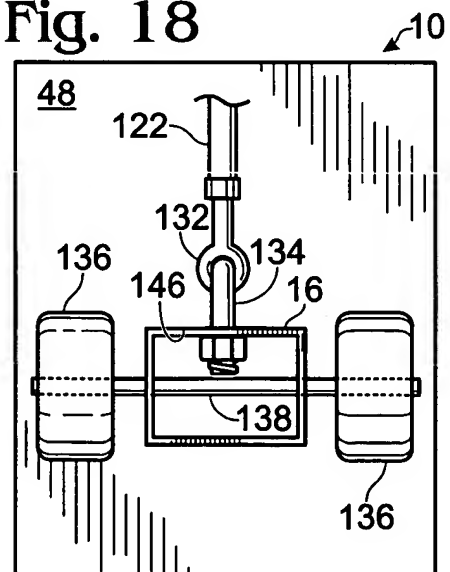


Fig. 19

↑ 20

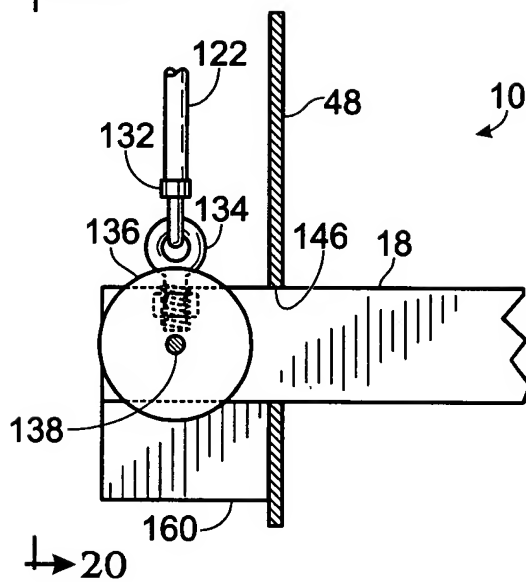


Fig. 20

↖ 10

